2020 IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2020)

July 29-31, 2020, Suzhou, China

Call for Papers

www.nusri.cn/imws-amp2020

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IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2020) is co-organized by National University of Singapore Suzhou Research Institute (NUSRI), East China Research Institute of Microelectronics, Northwestern Polytechnical University, Science and Technology on Electromagnetic Compatibility Laboratory, Science and Technology on Monolithic Integrated Circuits and Modules Laboratory, and Suzhou Science and Technology Association. The purpose of this new platform is to boost technical and educational activities as well as exchanges and collaborations within the international microwave community.

IMWS-AMP 2020 will be held in Suzhou, China on **July 29-31, 2020**. IMWS-AMP 2020 will feature both invited and contributed papers. Distinguished researchers will be invited to deliver keynote speeches on technology trends and significant advances in relevant topics. Contributed papers are solicited for the same topics as listed below.

Topics

The topics include, but are not limited to, the following technical areas:

- Carbon nanotubes and 2D electronic and optoelectronic devices (e.g. graphene and beyond graphene)
- Wide bandgap and other emerging semiconductor materials (e.g. ionic materials) based electronic devices: characterization, modelling and design
- Advanced silicon, integrated passive devices and through substrate via
- Low-temperature co-fired ceramic and liquid crystal polymer based microwave devices
- Large-area printing, inkjet printing and 3D printing materials and processes for RF and THz applications
- Engineered metamaterials and plasmonics for absorption, cloaking, and wave manipulation
- Ferromagnetic materials and superconducting materials
- Spin-wave and magnetic crystal materials
- Passive/active microwave and terahertz devices (material characterization, fabrications, and applications)
- Antennas with advanced/complex/artificial materials and processes

Electronic Paper Submission:

Prospective authors are invited to submit manuscripts in electronic (PDF) format only. All papers must be written in English and limited to three pages including text, references, and figures. A template is available on the IMWS-AMP 2020 website. Papers submitted will be peer reviewed and all papers presented at the conference will be included in IEEE Xplore pending quality review.

Special Issues in IEEE Transactions on Microwave Theory and Techniques (IEEE T-MTT) and Applied Computational Electromagnetic Society (ACES) Journal:

Authors of all papers presented at IEEE IMWS-AMP 2020 are invited to submit an expanded version of their papers to (1) a Mini-Special Issue of IEEE T-MTT. Every paper will be reviewed by T-MTT in the same manner as all other regular submissions to this publication; or (2) Applied Computational Electromagnetic Society (ACES) Journal (SCI). Papers that have some computational results to validate measurements or to post process measured data are especially encouraged for submission.

Best Paper Awards:

Awards for Best Paper(s) and Best Student Paper(s) will be presented to the winners at the conference. The Awards Committee will judge the papers primarily on originality, significance, technical soundness, presentation, and reviewers' reports. To qualify for the Best Student Paper, the author must be a full-time student who presents, as the first author, the paper at the conference.

Important Dates:

Paper Submission Deadline:	~~February 23, 2020~~	May 31, 2020
Notification of Acceptance:	~~April 27, 2020~~	June 22, 2020
Final paper Submission:	~~May 18, 2020~~	July 10, 2020

Exhibitions:

Exhibition of company products is solicited for the areas related to the topics. Interested parties should contact the Conference Secretariat.

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